## **AMPLEON**

## Package outline

LGA-7x7-20-1  $7.00 \pm 0.10$ Terminal 1 **SECTION B-B** index area **SCALE 80:1** Cropped view  $-0.025 \pm 0.010$  (1) В  $7.00 \pm 0.10$ Section B-B С Solder resist **Exposed metal** DETAIL A // 0.050 C -(0.98)SCALE 50:1 See detail A  $0.98 \pm 0.10$ Ф 0.100 A <del>ф</del> 0.100 В 6.80 -0.50 (20x) 2.58 10  $\bigcirc$  0.050 5 <del>|</del>| F 11 2.45 6.80 4.90 15 Terminal 1 index area 1.03 (16x) 4.90 Tolerances unless otherwise stated: Revision: Package outline drawing: 30-Dec-19 Angle: ± 1° Revision date: Dimension: ± 0.10 units in mm. LGA-7x7-20-1 Third angle projection Sheet 1 of 2 **Publication** 



## Package outline

LGA-7x7-20-1

Drawing Notes	
Item	Description
1	Metal thickness of solder pads.
2	Flatness with respect to exposed metal

Package outline drawing:

LGA-7x7-20-1

units in mm.

Tolerances unless otherwise stated:

Dimension: ± 0.10

A

Angle: ± 1° Re

Revision:

Revision date:

30-Dec-19

Third angle projection

Sheet 2 of 2